Reliability and Quality of Off-chip Interconnects in Advanced Packages in Perspective of High-Reliability Space Applications

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This presentation will discuss advanced packaging architectures and the reliability and quality of their off-chip interconnects. It will introduce common manufacturing process flows and materials used in these packages, along with construction analysis results. The discussion will focus on the effects of materials and manufacturing processes on the quality and reliability of interconnects, in the context of low-volume, high-mix, high-reliability space applications.